



Attorney Docket No. 0756-7719

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:

Shunpei YAMAZAKI et al.

Serial No. 10/581,674

Filed: June 5, 2006

For: METHOD FOR MANUFACTURING
THIN FILM INTEGRATED CIRCUIT
DEVICE, NONCONTACT THIN FILM
INTEGRATED CIRCUIT DEVICE
AND METHOD FOR
MANUFACTURING THE SAME, AND
IDTAG AND COIN INCLUDING THE
NONCONTACT THIN FILM
INTEGRATED CIRCUIT

) Group Art Unit: 2823

) Examiner: William D. Coleman

) CERTIFICATE OF MAILING

) I hereby certify that this correspondence is
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) Commissioner for Patents, P.O. Box 1450,
) Alexandria, VA 22313-1450, on January 21,
) 2009.

) Adrian M. Stampler

INTERVIEW SUMMARY AND AMENDMENT

Honorable Commissioner of Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

In response to the Official Action dated October 21, 2008, please consider the following amendments and remarks in connection with the above-identified application.

Amendments to the Claims are reflected in the listing of claims, which begins on page 2 of this paper.

Remarks begin on page 9 of this paper.